

# Interactive Screen 65" & 75"

An all-in-one solution designed with professional image engine and dedicated software that allows for a whole new level of multi-interactive system experience.

The T-Screen brings a visible difference to your presentations, especially for web conferencing, exhibitions, advertisements, whiteboarding, etc.



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# **Major Advantages**

## Multi Touch Technology

26-point infrared touch technology display for more interactive collaboration in training room, meeting room, classroom and more.

# **Dual USB Slot**

Ease of sharing HID (Human Interface Devices) such as mouse, keyboard, presentation pointer and etc. with front panel USB 2.0 slot.

## Video Conferencing

Support Windows based business-class video conferencing platforms for effective face-to-face interactions. Saves time and money on travelling.

# Windows Touch-Optimised System

Leverage your content with intuitive and distinctive user interactions that are touch optimised. Simply tap, swipe, pinch and rotate to get a global view of your content.

### **UHD LED Panel**

Ultra HD 3840 x 2160 widescreen resolution display for outstanding colour brightness and content clarity with best visual results.

# Rich User Experience

Powered by Windows for short learning curve, better usability and richer multimedia experience of a PC.

# Whiteboarding

Digital whiteboard tool for document annotation and unlimited note-taking. Users can annotate documents in different colours, shapes and even pen sizes.

# Screen Mirroring

Stream your content wirelessly to audience's devices, allowing everyone to stay connected and collaborate on your content.

Display		
Display Size	65"	75"
Display Type	D-LED (Direct LED Backlight)	
Aspect Ratio	16:9	
Active Area	1428.48mm (H) x 803.52mm (V)	1649.6mm (H) x 927.936mm (V)
Resolution	UHD 4K (384	40 x 2160p)
Brightness	350 cd/m <sup>2</sup>	
Contrast Ratio	5000:1	4000:1
Refresh Rate	60	Hz
Display Colours	1.07 billion colours	
Response Time	8 ms	
Viewing Angle	178°	
Glass Type	Anti-Glare	
Glass Hardness	9H (pencil), 7(Mohs)	
Audio	2 x 15W	
Buttons	Homepage, Power On & Sleep	
Interactive		
Touch Technology	Surface Light W	Jave (Infrared)
Touch Points	Surface Light Wave (Infrared)	
Contact Height	32 touch on Windows, 10 touch on Android 1.8mm	
Touch Accuracy	1.8mm 1mm	
Touch Response Time	4 ms	
Compatibility		
Touch Tools	Windows, Mac, Android, Linux, Chrome Finger or Pen	
	Filiger	oi reii
I/O Interface		
	USB2.0 for Android, USB3.0 for Windows, USB for Touch, HDMI In	
Front Connectivity		
•	Touch USB x 1, HDMI In x 2, RJ45 x 1, Audio In x 1, VG Built in Wi-Fi, SPDIF Out x 1, RS232 UART x 1,	GA In x 1, AV In x 1, Earphone Out x 1, TF Reader x
Android Connectivity	Touch USB x 1, HDMI In x 2, RJ45 x 1, Audio In x 1, VG	GA In x 1, AV In x 1, Earphone Out x 1, TF Reader x
Android Connectivity  OPS (PC Module)	Touch USB x 1, HDMI In x 2, RJ45 x 1, Audio In x 1, VG	GA In x 1, AV In x 1, Earphone Out x 1, TF Reader x DP x 1, USB 2.0 x 1, USB 3.0 x 1, HDMI Out x 1
Android Connectivity  OPS (PC Module)  Operating Systems	Touch USB x 1, HDMI In x 2, RJ45 x 1, Audio In x 1, VG Built in Wi-Fi, SPDIF Out x 1, RS232 UART x 1,	GA In x 1, AV In x 1, Earphone Out x 1, TF Reader x DP x 1, USB 2.0 x 1, USB 3.0 x 1, HDMI Out x 1 DP ro 64-bit
Android Connectivity  OPS (PC Module)  Operating Systems Chipset	Touch USB x 1, HDMI In x 2, RJ45 x 1, Audio In x 1, VG Built in Wi-Fi, SPDIF Out x 1, RS232 UART x 1, Windows 10	GA In x 1, AV In x 1, Earphone Out x 1, TF Reader x DP x 1, USB 2.0 x 1, USB 3.0 x 1, HDMI Out x 1 Pro 64-bit GA1151
OPS (PC Module) Operating Systems Chipset Processor RAM (DDR4 SODIMM)	Touch USB x 1, HDMI In x 2, RJ45 x 1, Audio In x 1, VG Built in Wi-Fi, SPDIF Out x 1, RS232 UART x 1, Windows 10 Intel LG	GA In x 1, AV In x 1, Earphone Out x 1, TF Reader x DP x 1, USB 2.0 x 1, USB 3.0 x 1, HDMI Out x 1  D Pro 64-bit GA1151 or above
Android Connectivity  OPS (PC Module)  Operating Systems  Chipset  Processor  RAM (DDR4 SODIMM)	Touch USB x 1, HDMI In x 2, RJ45 x 1, Audio In x 1, VG Built in Wi-Fi, SPDIF Out x 1, RS232 UART x 1, Windows 10 Intel LG i5 6th GEN	GA In x 1, AV In x 1, Earphone Out x 1, TF Reader x DP x 1, USB 2.0 x 1, USB 3.0 x 1, HDMI Out x 1  D Pro 64-bit GA1151 or above t up to 32GB
Android Connectivity  OPS (PC Module)  Operating Systems  Chipset  Processor  RAM (DDR4 SODIMM)  Storage	Touch USB x 1, HDMI In x 2, RJ45 x 1, Audio In x 1, VG Built in Wi-Fi, SPDIF Out x 1, RS232 UART x 1,  Windows 10 Intel LG i5 6th GEN 8GB; Support	GA In x 1, AV In x 1, Earphone Out x 1, TF Reader x DP x 1, USB 2.0 x 1, USB 3.0 x 1, HDMI Out x 1  D Pro 64-bit GA1151 or above t up to 32GB + 1TB HDD
Android Connectivity  OPS (PC Module)  Operating Systems  Chipset  Processor  RAM (DDR4 SODIMM)  Storage  I/O Interface	Touch USB x 1, HDMI In x 2, RJ45 x 1, Audio In x 1, VG Built in Wi-Fi, SPDIF Out x 1, RS232 UART x 1,  Windows 10 Intel LG i5 6th GEN 8GB; Support	GA In x 1, AV In x 1, Earphone Out x 1, TF Reader x DP x 1, USB 2.0 x 1, USB 3.0 x 1, HDMI Out x 1  D Pro 64-bit GA1151 or above t up to 32GB + 1TB HDD
Android Connectivity  OPS (PC Module) Operating Systems Chipset Processor RAM (DDR4 SODIMM) Storage I/O Interface Whiteboarding Module - Android On-Board	Touch USB x 1, HDMI In x 2, RJ45 x 1, Audio In x 1, VG Built in Wi-Fi, SPDIF Out x 1, RS232 UART x 1,  Windows 10 Intel LG i5 6th GEN 8GB; Support	SA In x 1, AV In x 1, Earphone Out x 1, TF Reader x DP x 1, USB 2.0 x 1, USB 3.0 x 1, HDMI Out x 1  D Pro 64-bit SA1151 or above t up to 32GB + 1TB HDD AN x 1, Mic In x 1 / Line Out x 1, VGA x 1
Android Connectivity  OPS (PC Module) Operating Systems Chipset Processor RAM (DDR4 SODIMM) Storage I/O Interface Whiteboarding Module - Android On-Board Android OS	Touch USB x 1, HDMI In x 2, RJ45 x 1, Audio In x 1, VG Built in Wi-Fi, SPDIF Out x 1, RS232 UART x 1,  Windows 10 Intel LG i5 6th GEN 8GB; Support SSD 256GB USB 3.0 x 2, USB 2.0 x 4, HDMI Out x 1, L	GA In x 1, AV In x 1, Earphone Out x 1, TF Reader x DP x 1, USB 2.0 x 1, USB 3.0 x 1, HDMI Out x 1  D Pro 64-bit GA1151 or above t up to 32GB + 1TB HDD AN x 1, Mic In x 1 / Line Out x 1, VGA x 1  id 8.0
Android Connectivity  OPS (PC Module)  Operating Systems  Chipset  Processor  RAM (DDR4 SODIMM)  Storage  I/O Interface  Whiteboarding Module - Android On-Board  Android OS  Chipset	Touch USB x 1, HDMI In x 2, RJ45 x 1, Audio In x 1, VG Built in Wi-Fi, SPDIF Out x 1, RS232 UART x 1,  Windows 10 Intel LG i5 6th GEN 8GB; Support SSD 256GB USB 3.0 x 2, USB 2.0 x 4, HDMI Out x 1, L	GA In x 1, AV In x 1, Earphone Out x 1, TF Reader x DP x 1, USB 2.0 x 1, USB 3.0 x 1, HDMI Out x 1  D Pro 64-bit GA1151 or above t up to 32GB + 1TB HDD AN x 1, Mic In x 1 / Line Out x 1, VGA x 1  id 8.0 on 811
Android Connectivity  OPS (PC Module)  Operating Systems  Chipset  Processor  RAM (DDR4 SODIMM)  Storage  I/O Interface  Whiteboarding Module - Android On-Board  Android OS  Chipset  CPU	Touch USB x 1, HDMI In x 2, RJ45 x 1, Audio In x 1, VG Built in Wi-Fi, SPDIF Out x 1, RS232 UART x 1,  Windows 10 Intel LG i5 6th GEN 8GB; Support SSD 256GB USB 3.0 x 2, USB 2.0 x 4, HDMI Out x 1, L  Andro Hisilica	GA In x 1, AV In x 1, Earphone Out x 1, TF Reader x DP x 1, USB 2.0 x 1, USB 3.0 x 1, HDMI Out x 1  Pro 64-bit GA1151 or above t up to 32GB + 1TB HDD AN x 1, Mic In x 1 / Line Out x 1, VGA x 1  id 8.0 on 811 ore A53 / 1.5GHz / Quad-Core
Android Connectivity  OPS (PC Module) Operating Systems Chipset Processor RAM (DDR4 SODIMM) Storage I/O Interface Whiteboarding Module - Android On-Board Android OS Chipset CPU GPU	Touch USB x 1, HDMI In x 2, RJ45 x 1, Audio In x 1, VG Built in Wi-Fi, SPDIF Out x 1, RS232 UART x 1,  Windows 10 Intel LG i5 6th GEN 8GB; Support SSD 256GB USB 3.0 x 2, USB 2.0 x 4, HDMI Out x 1, L  Andro Hisilico Dual-core ARM A73 and dual-c	GA In x 1, AV In x 1, Earphone Out x 1, TF Reader x DP x 1, USB 2.0 x 1, USB 3.0 x 1, HDMI Out x 1  Pro 64-bit GA1151 or above t up to 32GB + 1TB HDD AN x 1, Mic In x 1 / Line Out x 1, VGA x 1  id 8.0 on 811 ore A53 / 1.5GHz / Quad-Core 51
Android Connectivity  OPS (PC Module) Operating Systems Chipset Processor RAM (DDR4 SODIMM) Storage I/O Interface Whiteboarding Module - Android On-Board Android OS Chipset CPU GPU RAM (DDR)	Touch USB x 1, HDMI In x 2, RJ45 x 1, Audio In x 1, VG Built in Wi-Fi, SPDIF Out x 1, RS232 UART x 1,  Windows 10 Intel LG i5 6th GEN 8GB; Support SSD 256GB USB 3.0 x 2, USB 2.0 x 4, HDMI Out x 1, L  Andro Hisilico Dual-core ARM A73 and dual-c	GA In x 1, AV In x 1, Earphone Out x 1, TF Reader x DP x 1, USB 2.0 x 1, USB 3.0 x 1, HDMI Out x 1  D Pro 64-bit GA1151 or above t up to 32GB + 1TB HDD AN x 1, Mic In x 1 / Line Out x 1, VGA x 1  id 8.0 on 811 ore A53 / 1.5GHz / Quad-Core 61
Android Connectivity  OPS (PC Module) Operating Systems Chipset Processor RAM (DDR4 SODIMM) Storage I/O Interface Whiteboarding Module - Android On-Board Android OS Chipset CPU GPU RAM (DDR) EMMC	Touch USB x 1, HDMI In x 2, RJ45 x 1, Audio In x 1, VG Built in Wi-Fi, SPDIF Out x 1, RS232 UART x 1,  Windows 10 Intel LG i5 6th GEN 8GB; Support SSD 256GB USB 3.0 x 2, USB 2.0 x 4, HDMI Out x 1, L  Andro Hisilico Dual-core ARM A73 and dual-c G5	GA In x 1, AV In x 1, Earphone Out x 1, TF Reader x DP x 1, USB 2.0 x 1, USB 3.0 x 1, HDMI Out x 1  D Pro 64-bit GA1151 or above t up to 32GB + 1TB HDD AN x 1, Mic In x 1 / Line Out x 1, VGA x 1  id 8.0 on 811 ore A53 / 1.5GHz / Quad-Core GB GB
Android Connectivity  OPS (PC Module) Operating Systems Chipset Processor RAM (DDR4 SODIMM) Storage I/O Interface Whiteboarding Module - Android On-Board Android OS Chipset CPU GPU RAM (DDR) EMMC Wi-Fi Enabled	Touch USB x 1, HDMI In x 2, RJ45 x 1, Audio In x 1, VG Built in Wi-Fi, SPDIF Out x 1, RS232 UART x 1,  Windows 10 Intel LG i5 6th GEN 8GB; Support SSD 256GB USB 3.0 x 2, USB 2.0 x 4, HDMI Out x 1, L  Andro Hisilico Dual-core ARM A73 and dual-c G5 4G 320	GA In x 1, AV In x 1, Earphone Out x 1, TF Reader x DP x 1, USB 2.0 x 1, USB 3.0 x 1, HDMI Out x 1  D Pro 64-bit GA1151 or above t up to 32GB + 1TB HDD AN x 1, Mic In x 1 / Line Out x 1, VGA x 1  id 8.0 on 811 ore A53 / 1.5GHz / Quad-Core GB GB
Android Connectivity  OPS (PC Module) Operating Systems Chipset Processor RAM (DDR4 SODIMM) Storage I/O Interface Whiteboarding Module - Android On-Board Android OS Chipset CPU GPU RAM (DDR) EMMC Wi-Fi Enabled Power Supply	Touch USB x 1, HDMI In x 2, RJ45 x 1, Audio In x 1, VG Built in Wi-Fi, SPDIF Out x 1, RS232 UART x 1,  Windows 10 Intel LG i5 6th GEN 8GB; Support SSD 256GB USB 3.0 x 2, USB 2.0 x 4, HDMI Out x 1, L  Andro Hisilico Dual-core ARM A73 and dual-c G5 4G 320	GA In x 1, AV In x 1, Earphone Out x 1, TF Reader x DP x 1, USB 2.0 x 1, USB 3.0 x 1, HDMI Out x 1  D Pro 64-bit GA1151 or above t up to 32GB + 1TB HDD AN x 1, Mic In x 1 / Line Out x 1, VGA x 1  id 8.0 on 811 ore A53 / 1.5GHz / Quad-Core 61 68 68 68
Android Connectivity  OPS (PC Module) Operating Systems Chipset Processor RAM (DDR4 SODIMM) Storage I/O Interface Whiteboarding Module - Android On-Board Android OS Chipset CPU GPU RAM (DDR) EMMC Wi-Fi Enabled Power Supply Power	Touch USB x 1, HDMI In x 2, RJ45 x 1, Audio In x 1, VG Built in Wi-Fi, SPDIF Out x 1, RS232 UART x 1,  Windows 10 Intel LG i5 6th GEN 8GB; Support SSD 256GB USB 3.0 x 2, USB 2.0 x 4, HDMI Out x 1, L  Andro Hisilico Dual-core ARM A73 and dual-c G5 4G 320 Ye  AC 100	GA In x 1, AV In x 1, Earphone Out x 1, TF Reader x DP x 1, USB 2.0 x 1, USB 3.0 x 1, HDMI Out x 1  D Pro 64-bit GA1151 or above t up to 32GB + 1TB HDD AN x 1, Mic In x 1 / Line Out x 1, VGA x 1  id 8.0 on 811 ore A53 / 1.5GHz / Quad-Core G1 GB GB GB es
Android Connectivity  OPS (PC Module) Operating Systems Chipset Processor RAM (DDR4 SODIMM) Storage I/O Interface Whiteboarding Module - Android On-Board Android OS Chipset CPU GPU RAM (DDR) EMMC Wi-Fi Enabled Power Supply Power Power Consumption	Touch USB x 1, HDMI In x 2, RJ45 x 1, Audio In x 1, VG Built in Wi-Fi, SPDIF Out x 1, RS232 UART x 1,  Windows 10 Intel LG i5 6th GEN 8GB; Support SSD 256GB USB 3.0 x 2, USB 2.0 x 4, HDMI Out x 1, L  Andro Hisilico Dual-core ARM A73 and dual-c G5 4G 320 Ye  AC 100 250W	GA In x 1, AV In x 1, Earphone Out x 1, TF Reader x DP x 1, USB 2.0 x 1, USB 3.0 x 1, HDMI Out x 1  D Pro 64-bit GA1151 or above t up to 32GB + 1TB HDD AN x 1, Mic In x 1 / Line Out x 1, VGA x 1  id 8.0 on 811 ore A53 / 1.5GHz / Quad-Core G1 GB GB GB es - 240V 350W
Android Connectivity  OPS (PC Module) Operating Systems Chipset Processor RAM (DDR4 SODIMM) Storage I/O Interface Whiteboarding Module - Android On-Board Android OS Chipset CPU GPU RAM (DDR) EMMC Wi-Fi Enabled Power Supply Power Power Consumption Power Consumption (Standby)	Touch USB x 1, HDMI In x 2, RJ45 x 1, Audio In x 1, VG Built in Wi-Fi, SPDIF Out x 1, RS232 UART x 1,  Windows 10 Intel LG i5 6th GEN 8GB; Support SSD 256GB USB 3.0 x 2, USB 2.0 x 4, HDMI Out x 1, L  Andro Hisilico Dual-core ARM A73 and dual-c G5 4G 320 Ye  AC 100	GA In x 1, AV In x 1, Earphone Out x 1, TF Reader x DP x 1, USB 2.0 x 1, USB 3.0 x 1, HDMI Out x 1  D Pro 64-bit GA1151 or above t up to 32GB + 1TB HDD AN x 1, Mic In x 1 / Line Out x 1, VGA x 1  id 8.0 on 811 ore A53 / 1.5GHz / Quad-Core G1 GB GB GB es - 240V 350W
Android Connectivity  OPS (PC Module) Operating Systems Chipset Processor RAM (DDR4 SODIMM) Storage I/O Interface Whiteboarding Module - Android On-Board Android OS Chipset CPU GPU RAM (DDR) EMMC Wi-Fi Enabled Power Supply Power Power Consumption Power Consumption (Standby) Dimensions & Weight	Touch USB x 1, HDMI In x 2, RJ45 x 1, Audio In x 1, VG Built in Wi-Fi, SPDIF Out x 1, RS232 UART x 1,  Windows 10 Intel LG i5 6th GEN 8GB; Support SSD 256GB USB 3.0 x 2, USB 2.0 x 4, HDMI Out x 1, L  Andro Hisilico Dual-core ARM A73 and dual-c G5 4G 320 Ye  AC 100 250W	GA In x 1, AV In x 1, Earphone Out x 1, TF Reader x DP x 1, USB 2.0 x 1, USB 3.0 x 1, HDMI Out x 1  D Pro 64-bit GA1151 or above t up to 32GB + 1TB HDD AN x 1, Mic In x 1 / Line Out x 1, VGA x 1  id 8.0 on 811 ore A53 / 1.5GHz / Quad-Core G1 GB GB GB es - 240V 350W
Android Connectivity  OPS (PC Module) Operating Systems Chipset Processor RAM (DDR4 SODIMM) Storage I/O Interface Whiteboarding Module - Android On-Board Android OS Chipset CPU GPU RAM (DDR) EMMC Wi-Fi Enabled Power Supply Power Power Consumption Power Consumption (Standby) Dimensions & Weight Product Dimensions	Touch USB x 1, HDMI In x 2, RJ45 x 1, Audio In x 1, VG Built in Wi-Fi, SPDIF Out x 1, RS232 UART x 1,  Windows 10 Intel LG i5 6th GEN 8GB; Support SSD 256GB USB 3.0 x 2, USB 2.0 x 4, HDMI Out x 1, L  Andro Hisilico Dual-core ARM A73 and dual-c G5 4G 320 Ye  AC 100 250W	GA In x 1, AV In x 1, Earphone Out x 1, TF Reader x DP x 1, USB 2.0 x 1, USB 3.0 x 1, HDMI Out x 1  D Pro 64-bit GA1151 or above t up to 32GB + 1TB HDD AN x 1, Mic In x 1 / Line Out x 1, VGA x 1  id 8.0 on 811 ore A53 / 1.5GHz / Quad-Core G1 GB GB GB es - 240V 350W
Android Connectivity  OPS (PC Module) Operating Systems Chipset Processor RAM (DDR4 SODIMM) Storage I/O Interface Whiteboarding Module - Android On-Board Android OS Chipset CPU GPU RAM (DDR) EMMC Wi-Fi Enabled Power Supply Power Power Consumption Power Consumption (Standby) Dimensions & Weight Product Dimensions (W x H x D)	Touch USB x 1, HDMI In x 2, RJ45 x 1, Audio In x 1, VG Built in Wi-Fi, SPDIF Out x 1, RS232 UART x 1,  Windows 10 Intel LG i5 6th GEN 8GB; Support SSD 256GB USB 3.0 x 2, USB 2.0 x 4, HDMI Out x 1, L  Andro Hisilice Dual-core ARM A73 and dual-c G5 4G 320 Ye  AC 100 250W	GA In x 1, AV In x 1, Earphone Out x 1, TF Reader x DP x 1, USB 2.0 x 1, USB 3.0 x 1, HDMI Out x 1  D Pro 64-bit GA1151 Or above t up to 32GB + 1TB HDD AN x 1, Mic In x 1 / Line Out x 1, VGA x 1  id 8.0 on 811 ore A53 / 1.5GHz / Quad-Core G1 GB GB es - 240V 350W
Android Connectivity  OPS (PC Module) Operating Systems Chipset Processor RAM (DDR4 SODIMM) Storage I/O Interface Whiteboarding Module - Android On-Board Android OS Chipset CPU GPU RAM (DDR) EMMC Wi-Fi Enabled Power Supply Power Power Consumption Power Consumption (Standby) Dimensions & Weight Product Dimensions (Wx H x D) Product Dimensions (Package)	Touch USB x 1, HDMI In x 2, RJ45 x 1, Audio In x 1, VG Built in Wi-Fi, SPDIF Out x 1, RS232 UART x 1,  Windows 10 Intel LG i5 6th GEN 8GB; Support SSD 256GB USB 3.0 x 2, USB 2.0 x 4, HDMI Out x 1, L  Andro Hisilice Dual-core ARM A73 and dual-c G5 4G 320 Ye  AC 100 250W	GA In x 1, AV In x 1, Earphone Out x 1, TF Reader x DP x 1, USB 2.0 x 1, USB 3.0 x 1, HDMI Out x 1  D Pro 64-bit GA1151 Or above t up to 32GB + 1TB HDD AN x 1, Mic In x 1 / Line Out x 1, VGA x 1  id 8.0 on 811 ore A53 / 1.5GHz / Quad-Core G1 GB GB es - 240V 350W
Android Connectivity  OPS (PC Module) Operating Systems Chipset Processor RAM (DDR4 SODIMM) Storage I/O Interface Whiteboarding Module - Android On-Board Android OS Chipset CPU GPU RAM (DDR) EMMC Wi-Fi Enabled Power Supply Power Power Consumption Power Consumption (Standby) Dimensions & Weight Product Dimensions (Wx H x D) Product Dimensions (Package) (Wx H x D)	Touch USB x 1, HDMI In x 2, RJ45 x 1, Audio In x 1, VG Built in Wi-Fi, SPDIF Out x 1, RS232 UART x 1,  Windows 10 Intel LG i5 6th GEN 8GB; Support SSD 256GB USB 3.0 x 2, USB 2.0 x 4, HDMI Out x 1, L  Andro Hisilico Dual-core ARM A73 and dual-c G5 4G 320 Ye  AC 100 250W  <1 1516mm x 939.2mm x 102mm 1620mm x 1060mm x 240mm	SA In x 1, AV In x 1, Earphone Out x 1, TF Reader x 1 DP x 1, USB 2.0 x 1, USB 3.0 x 1, HDMI Out x 1  D Pro 64-bit SA1151 or above t up to 32GB + 1TB HDD AN x 1, Mic In x 1 / Line Out x 1, VGA x 1  id 8.0 on 811 ore A53 / 1.5GHz / Quad-Core S1 SB SB SS ~ 240V 350W W  1737.4mm x 1064.6mm x 112.3mm 1950mm x 1250mm x 240mm
Android Connectivity  OPS (PC Module) Operating Systems Chipset Processor RAM (DDR4 SODIMM) Storage I/O Interface Whiteboarding Module - Android On-Board Android OS Chipset CPU GPU RAM (DDR) EMMC Wi-Fi Enabled Power Supply Power Power Consumption Power Consumption (Standby) Dimensions & Weight Product Dimensions (Wx H x D) Product Dimensions (Package)	Touch USB x 1, HDMI In x 2, RJ45 x 1, Audio In x 1, VG Built in Wi-Fi, SPDIF Out x 1, RS232 UART x 1,  Windows 10 Intel LG IS 6th GEN 8GB; Support SSD 256GB USB 3.0 x 2, USB 2.0 x 4, HDMI Out x 1, L  Andro Hisilica Dual-core ARM A73 and dual-c GS 4G 320 Ye  AC 100 250W  < 1 1516mm x 939.2mm x 102mm	GA In x 1, AV In x 1, Earphone Out x 1, TF Reader x 2 DP x 1, USB 2.0 x 1, USB 3.0 x 1, HDMI Out x 1  D Pro 64-bit GA1151  or above t up to 32GB + 1TB HDD  AN x 1, Mic In x 1 / Line Out x 1, VGA x 1  id 8.0 on 811 ore A53 / 1.5GHz / Quad-Core G1 GB GB GB GS CS  ~ 240V  350W  W

#### Option : Mobile Stand

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